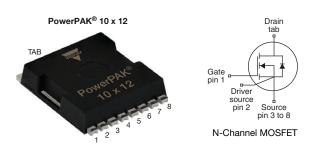
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Vishay Siliconix

EF Series Power MOSFET With Fast Body Diode



PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.075			
Q _g max. (nC)	63				
Q _{gs} (nC)	17				
Q _{gd} (nC)	9				
Configuration	Single				

FEATURES

- 4th generation E series technology
- Low figure of merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
- Welding
- Induction heating
- Motor drives
- Battery chargers
- Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK [®] 10 x12
Lead (Pb)-free and halogen-free	SiHK085N60EF-T1GE3

ABSOLUTE MAXIMUM RATINGS ($T_c = 25$ °C, unless otherwise noted)							
PARAMETER		SYMBOL	LIMIT	UNIT			
Drain-source voltage			V _{DS}	600	v		
Gate-source voltage			V _{GS}	± 30	v		
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C T _C = 100 °C		30			
	VGS at 10 V	T _C = 100 °C	ID	19	А		
Pulsed drain current ^a			I _{DM}	75			
Linear derating factor				1.47	W/°C		
Single pulse avalanche energy b			E _{AS}	173	mJ		
Maximum power dissipation			PD	184	W		
Operating junction and storage temperature ra	nge		T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope		T _J = 125 °C	dv/dt	100	V/ns		
Reverse diode dv/dt ^d		uv/ul	50	v/ns			

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 $\Omega, \, I_{AS}$ = 3.5 A

c. 1.6 mm from case

d. $I_{SD} \leq I_D$, di/dt = 100 A/µs, starting T_J = 25 °C





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THERMAL RESISTANCE RAT	INGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	- 50			°C 111			
Maximum junction-to-case (drain)	R _{thJC}	- 0.68				°C/W		
SPECIFICATIONS (T _J = 25 $^{\circ}$ C, t	unless otherwi	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static						-		
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 2	250 µA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C,	, I _D = 1 mA	-	0.56	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 2	250 µA	3.0	-	5.0	V
		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
Gate-source leakage	I _{GSS}	V _{GS} = ± 30 V			-	-	± 1	μA
Zara acta valtaga duain avuruant	I	V _{DS} =	= 480 V, V _G	_S = 0 V	-	-	1	μA
Zero gate voltage drain current	IDSS	V _{DS} = 480 V	, V _{GS} = 0 V	/, T _J = 125 °C	-	-	2	mA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	١	_D = 17 A	-	0.075	0.085	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 10 V, I _D =	= 17 A	-	16	-	S
Dynamic	-					•	•	•
Input capacitance	C _{iss}		V _{GS} = 0 V,		-	2733	-	
Output capacitance	C _{oss}	$V_{DS} = 100 V,$ f = 100 KHz		-	100	-	pF	
Reverse transfer capacitance	C _{rss}			-	3	-		
Effective output capacitance, energy related ^a	C _{o(er)}	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		-	107	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	645	-		
Total gate charge	Qg				-	42	63	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	V _{GS} = 10 V I _D = 17 A, V _{DS} = 480 V		-	17	-	nC
Gate-drain charge	Q _{gd}			20	-	9	-	1
Turn-on delay time	t _{d(on)}			-	32	64		
Rise time	t _r	V _{DD} =	V _{DD} = 480 V, I _D = 17 A,		-	75	113	
Turn-off delay time	t _{d(off)}	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 9.1 \Omega$		-	48	96	ns	
Fall time	t _f				-	53	80	
Gate input resistance	R _g	f = 1 MHz		0.3	0.7	1.4	Ω	
Drain-Source Body Diode Characterist								
Continuous source-drain diode current	١ _S	MOSFET sym showing the	MOSFET symbol		-	-	30	
Pulsed diode forward current	I _{SM}	p - n junction diode		-	-	75	A	
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V		-	-	1.2	V	
Reverse recovery time	t _{rr}	$T_{J} = 25 \text{ °C}, I_{F} = I_{S} = 17 \text{ A},$ di/dt = 100 A/µs, V _R = 400 V		- 1	109	218	ns	
Reverse recovery charge	Q _{rr}			-	0.6	1.2	μC	
Reverse recovery current	I _{RRM}			-	11	-	A	

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 V to 400 V

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 V to 400 V

c. When mounted on 1" x 1" FR4 board



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

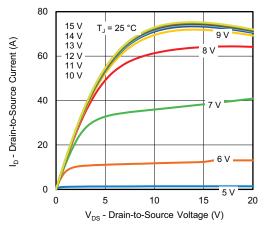


Fig. 1 - Typical Output Characteristics

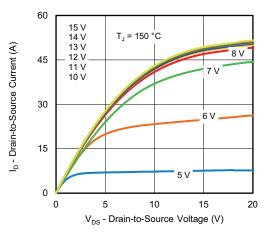


Fig. 2 - Typical Output Characteristics

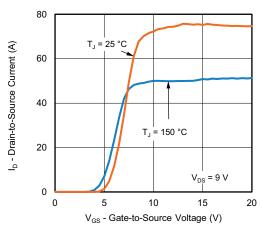


Fig. 3 - Typical Transfer Characteristics

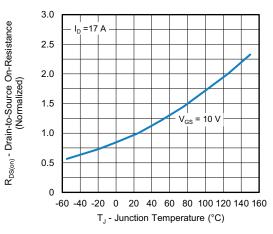


Fig. 4 - Normalized On-Resistance vs. Temperature

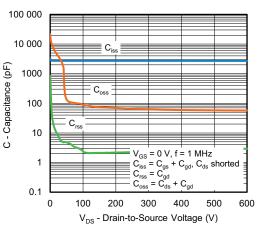
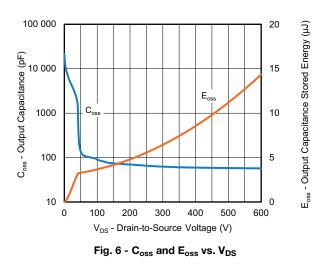


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



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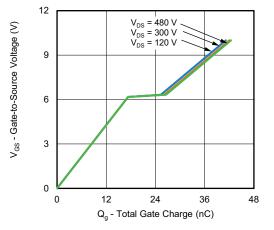


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

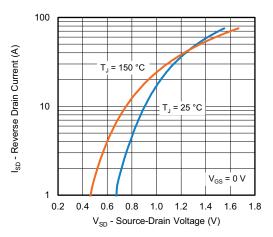


Fig. 8 - Typical Source-Drain Diode Forward Voltage

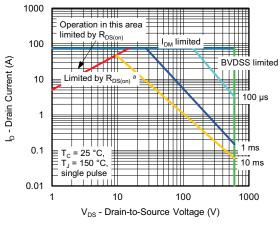


Fig. 9 - Maximum Safe Operating Area

Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

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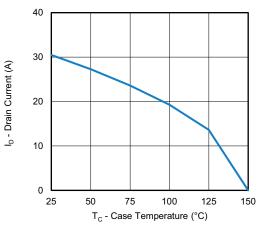


Fig. 10 - Maximum Drain Current vs. Case Temperature

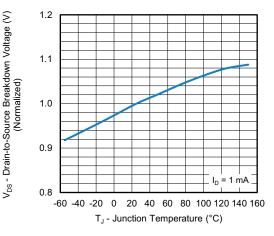
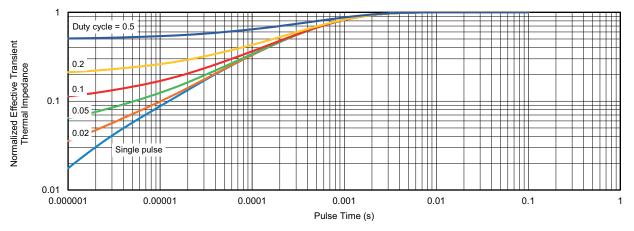


Fig. 11 - Temperature vs. Drain-to-Source Voltage



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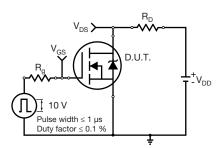


Fig. 13 - Switching Time Test Circuit

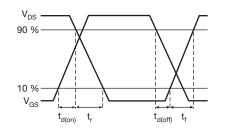


Fig. 14 - Switching Time Waveforms

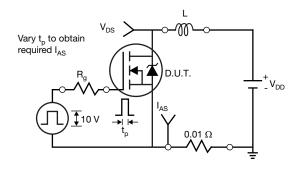


Fig. 15 - Unclamped Inductive Test Circuit

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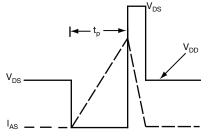


Fig. 16 - Unclamped Inductive Waveforms

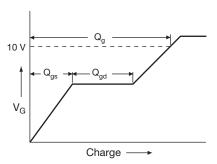
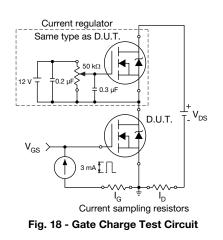


Fig. 17 - Basic Gate Charge Waveform



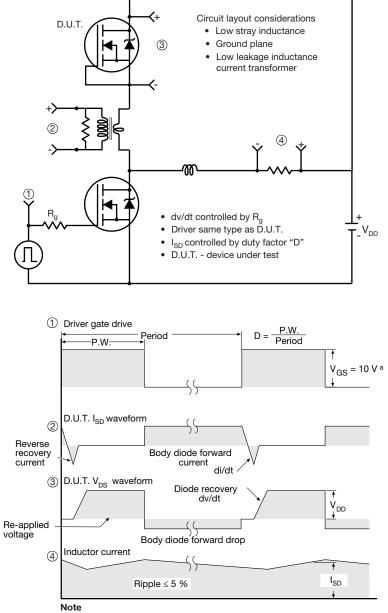
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Peak Diode Recovery dv/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 19 - For N-Channel

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